

RoHS  
Compliant

## Specifications

Dice material : InGaN/Sapphire  
Emmiting Colour : Blue  
Lens colour : Water clear  
Dominant Wavelength : 465nm  
Viewing angle : 130°  
Luminous intensity (IV) : 100mcd

## Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	120	mW
D.C Forward current	If	30	mA
Reverse Voltage	Vr	5	V
Operating Temperature	Top	-30 to +80	°C
Storage Temperature	Tstg.	-40 to +85	°C
Peak Current (1/10Duty Cycle,0.1ms Pulse Width.)	If (peak)	80	mA
Soldering Temperature	Tsol	Reflow Soldering: 260°C for 10 sec.	
Electric Static Discharge	ESD	300	V

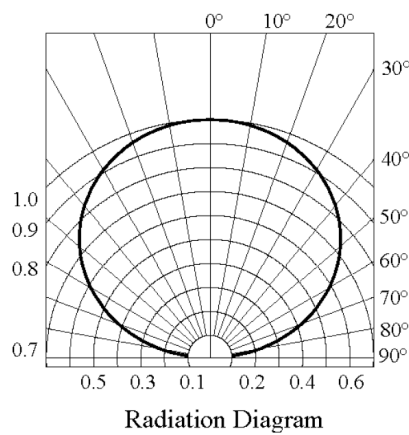
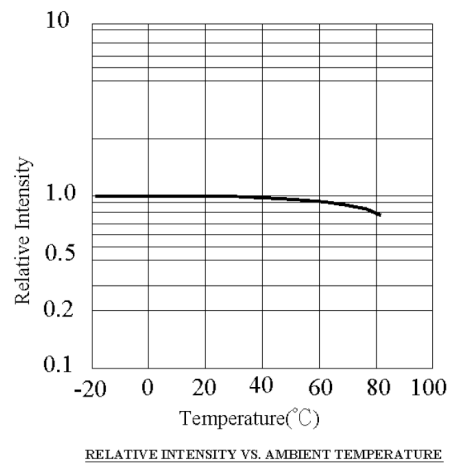
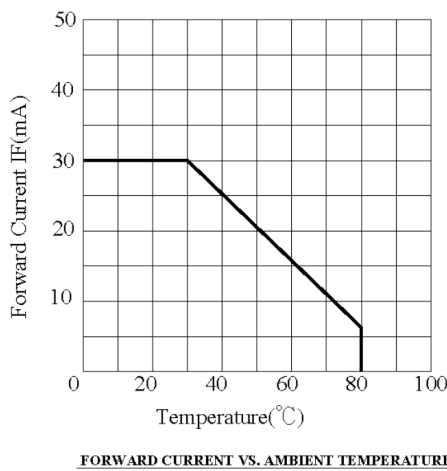
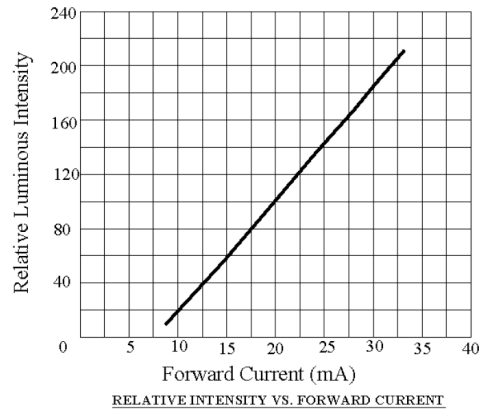
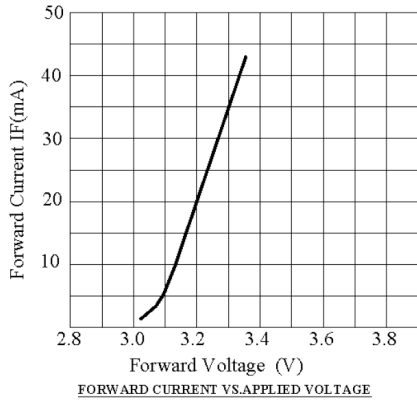
## Electrical and Optical Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	Iv	If=20mA	51.6	100		mcd
Forward Voltage	Vf	If=20mA		3.2	4	V
Peak Wavelength	$\lambda_p$					
Dominant Wavelength	$\lambda_d$	If=20mA		465		nm
Reverse Current	Ir	Vr=5V			50	$\mu$ A
Viewing Angle	2 $\theta$ 1/2	If=20mA		130		deg
Spectrum Line Halfwidth	$\Delta\lambda$	If=20mA		20		

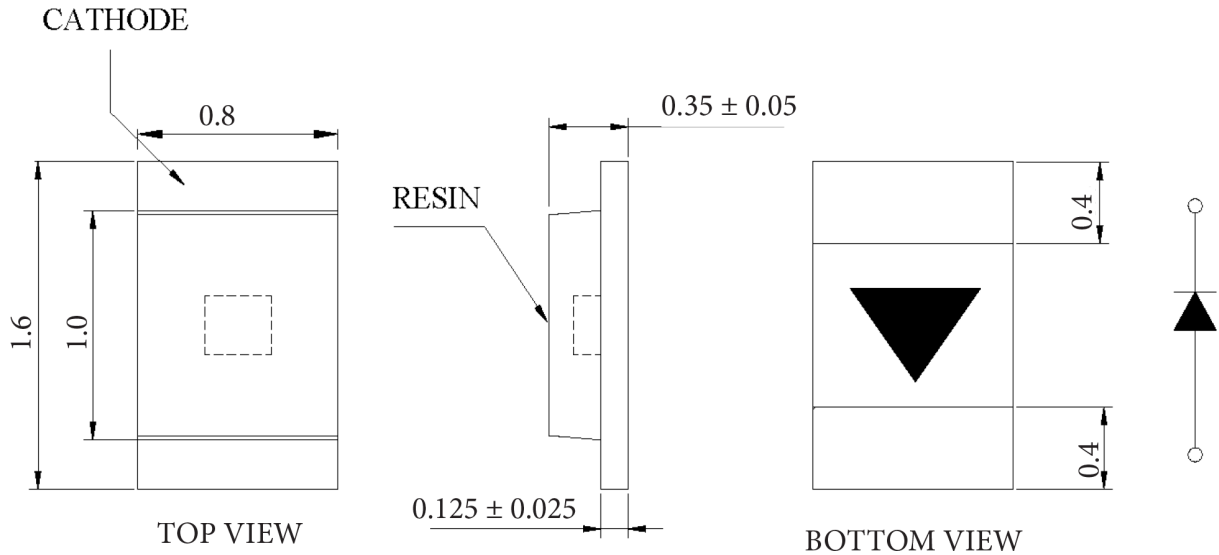
### Notes:

1. Tolerance of Luminous Intensity is  $\pm 10\%$
2. Tolerance of Forward Voltage is  $\pm 0.05V$
3. Tolerance of Dominant Wavelength is  $\pm 1nm$

## Typical Electrical/Optical Characteristic Curves (25°C Ambient Temperature Unless Otherwise Noted)



## Dimensions



Tolerance is  $\pm 0.1$ mm unless otherwise noted.

Dimensions : Millimetres

## Precautions in use:

### Storage

Recommend storage environment:

Temperature: 5°C to 30°C (41°F to 86°F)

Humidity: 60% RH Max.

Use within 7 days after opening of sealed vapor/ESD barrier bags.

If the LEDs have exceeded the storage time, baking should be performed using the following conditions.

Baking at : 60  $\pm$ 5°C for 24 hours.

Fold the opened bag firmly and keep in dry environment.

### Soldering

#### Reflow Soldering

Recommend use of upper and lower heater type reflow furnace.

260°C Max for up to 5 seconds, one time only.

Pre-heat is 150°C Max for up to 2 minutes Max.

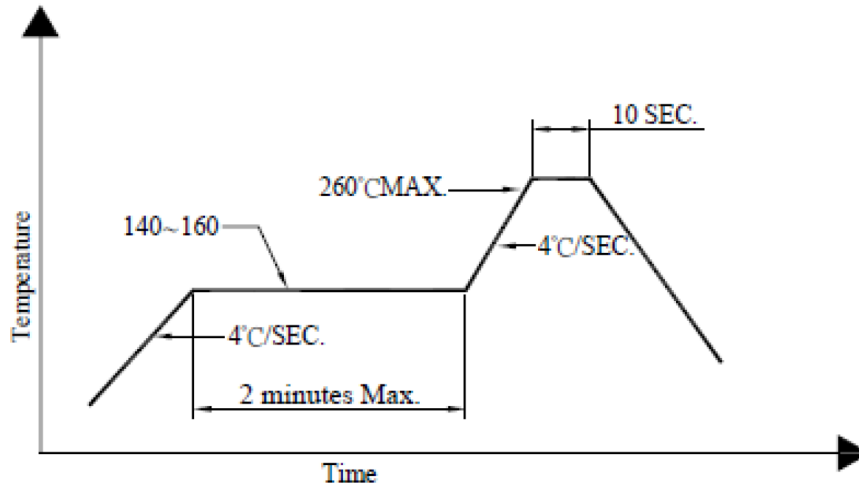
In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm.

### Cleaning

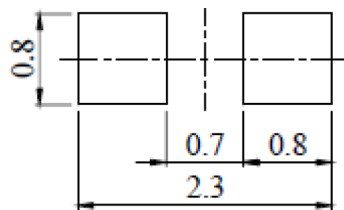
Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

Avoid using organic solvent. Recommend ultrasonic method 300W Max.

## Reflow Temp/Time



## Reflow Soldering Pad Dimensions



## Part Number Table

Description	Part Number
Chip LED, Blue, 465nm, 130°, 100mcd, Surface Mount	MP008259

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